CIRCUIT AND METHOD FOR PROVIDING INTERCONNECTIONS AMONG INDIVIDUAL INTEGRATED CIRCUIT CHIPS IN A MULTI-CHIP MODULE

Abstract

A multi-chip module ("MCM") and methods of operation and manufacture thereof. The MCM includes: (1) a substrate for supporting a plurality of separate integrated circuit (IC) chips thereon, (2) first and second separate IC chips mounted on the substrate, the first separate IC chip including first and second circuit portions coupled together by at least one signal conductor, and (3) interconnecting means that directly couples at least one signal conductor of the first separate IC chip to the second separate IC chip, the interconnecting means bypassing the second circuit portion of the first separate IC chip.